



Empa

Materials Science and Technology



ÉCOLE POLYTECHNIQUE
FÉDÉRALE DE LAUSANNE

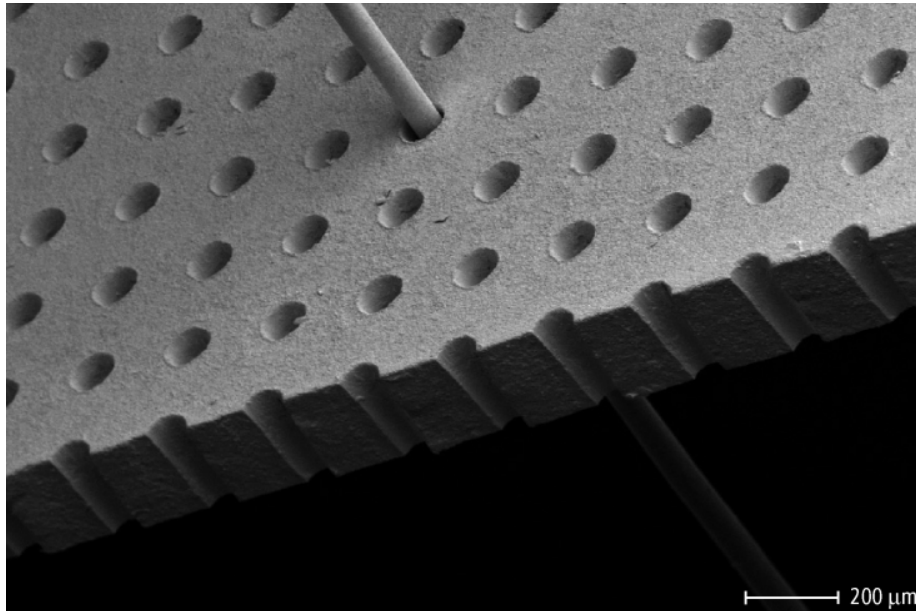
Laser Processing of Materials

Applications: Ultrafast Laser Ablation

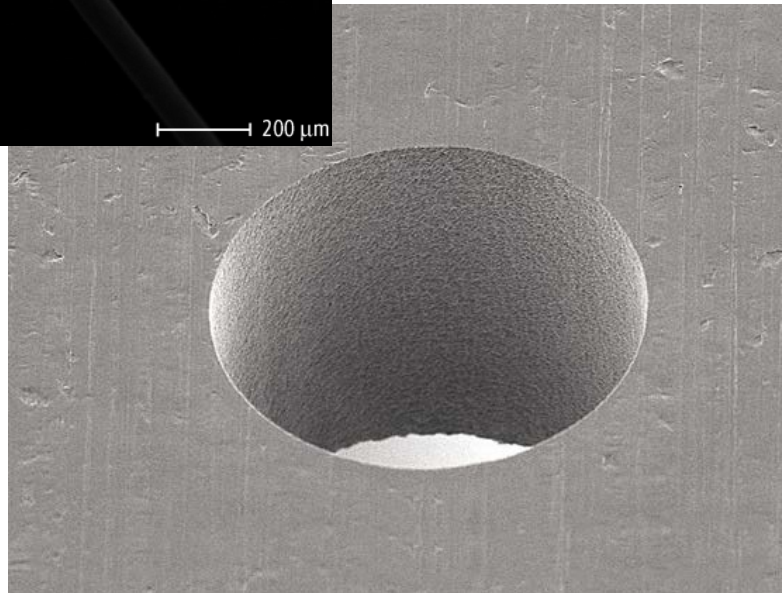
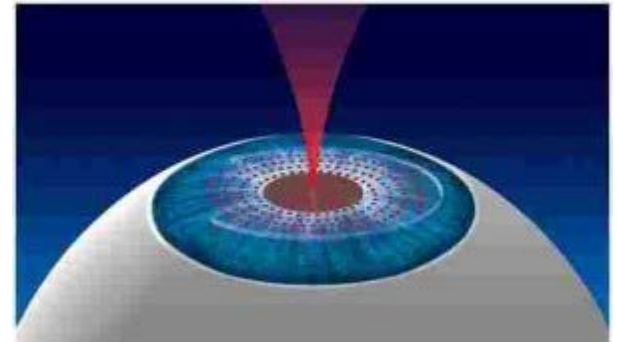
Patrik Hoffmann

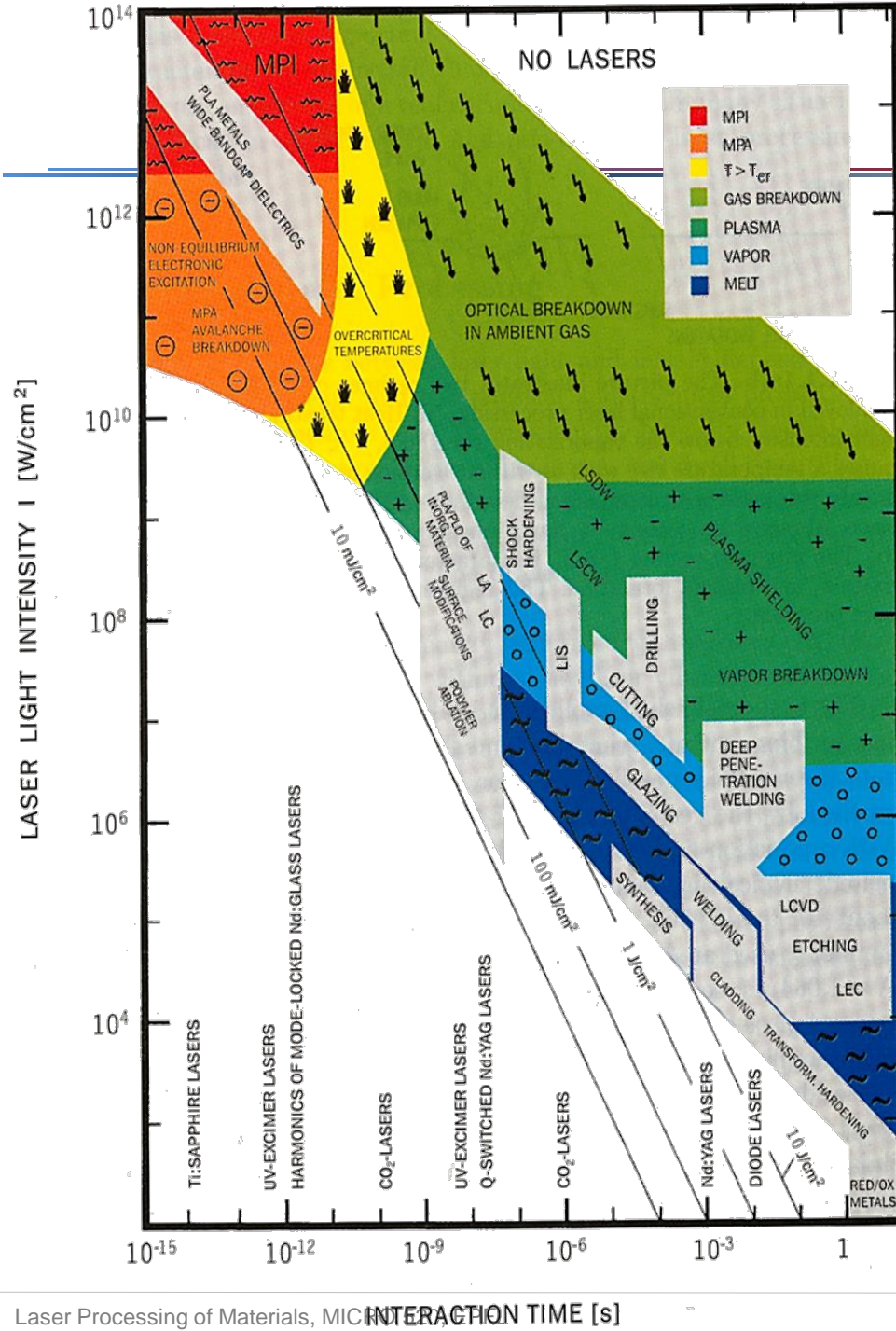
Applications: Ultrafast (modelocked) Lasers

high precision laser machining



**no blade cut
eye correction**





Application of lasers in materials processing:

Intensity-Time Diagram

PLA/PLD – pulsed laser ablation/
deposition

LA – laser annealing

LC – laser cleaning

LIS – laser induced isotope separation/IR –
laser photochemistry

MPA/MPI – multiphoton absorption
ionization

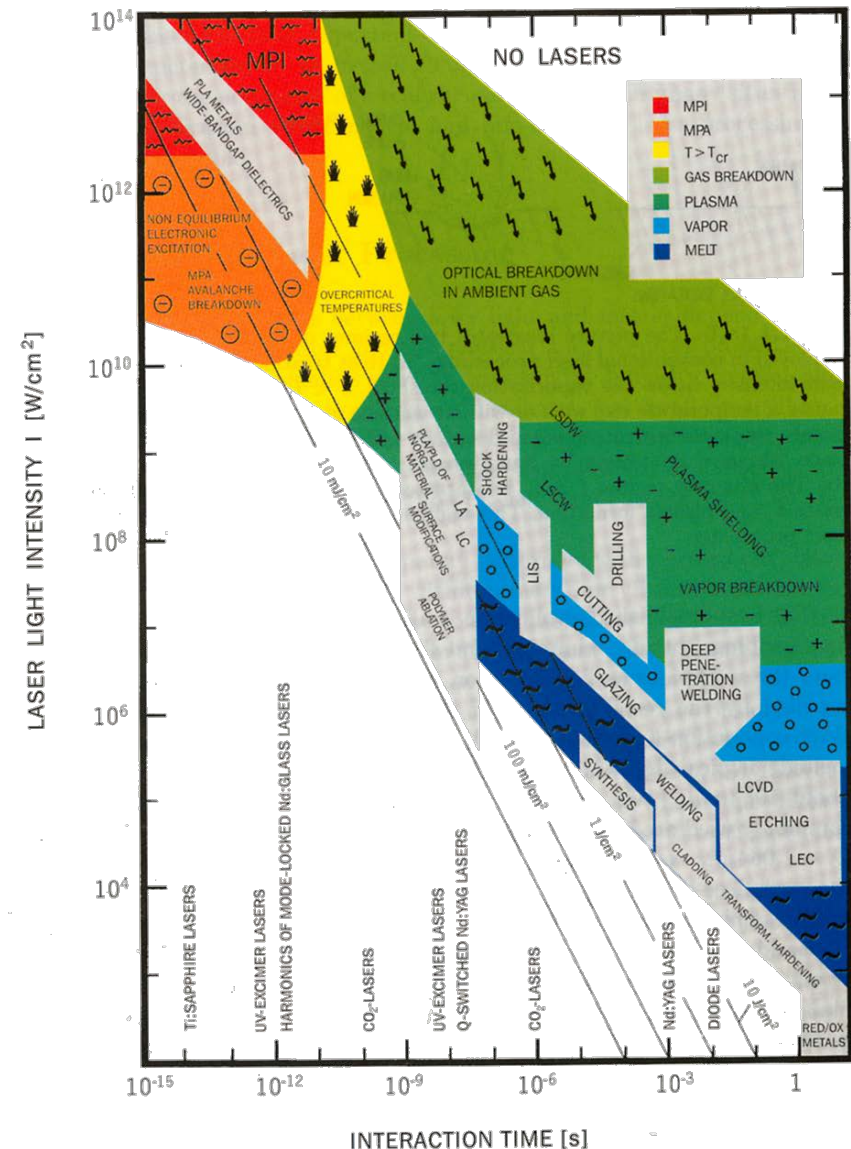
LSDW/LSCW – laser supported
detonation/combustion waves

LCVD – laser induced chemical vapour
deposition

LEC – laser induced electrochemical
plating/etching

RED/OX – long pulse or cw CO₂-laser
induced reduction/oxidation

D. Bäuerle; Laser Processing and
Chemistry, 3rd ed. Springer, Berlin,
2000



Laser Types: Pulsed & CW

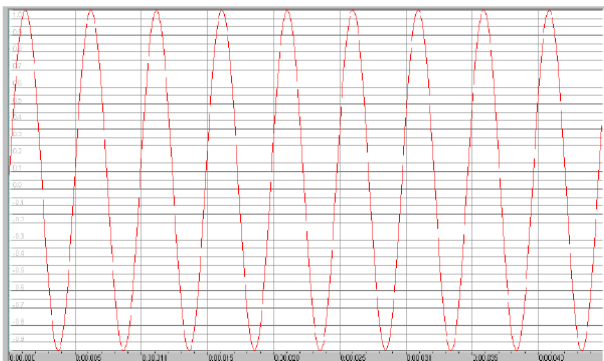
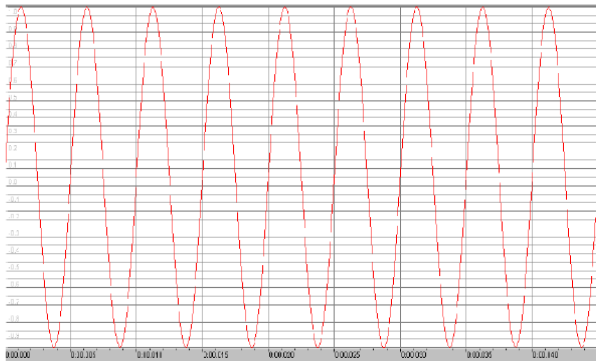
Type of laser	Pulse length determined by	Typical pulse length	Characteristic pulse peak power
Continuous wave (cw)	-	∞	Ws – kWs
Free running laser	Pump pulse length (flash lamp)	100 μ s – 1ms	kWs
Q-switched laser	Time constants of active material and modulating element	1 ns – 100 ns	MWs
Mode-locked laser	Number of coupled modes, pulse compression	10 fs – 10 ps	GWs

Why do you want very short pulses?

Mode-locking regime

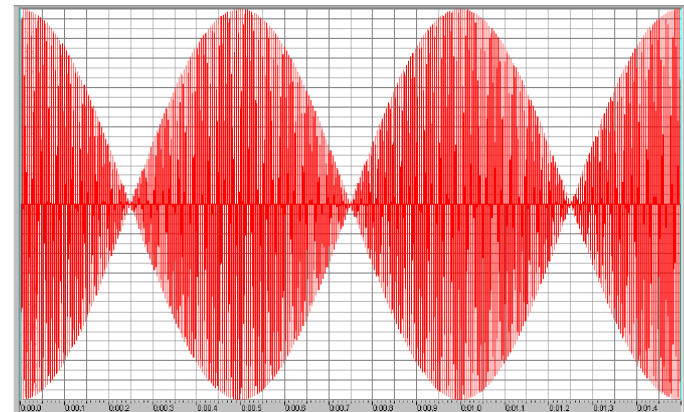
Mode-locked pulses – result of **interference** of many „locked“ (phase/frequency related) light waves

interference of waves with two different frequencies



t [s]

$$A_{S2}(t) = A_1(t) + A_2(t) = \sin(2\pi\nu_1 t) + \sin(2\pi\nu_2 t)$$



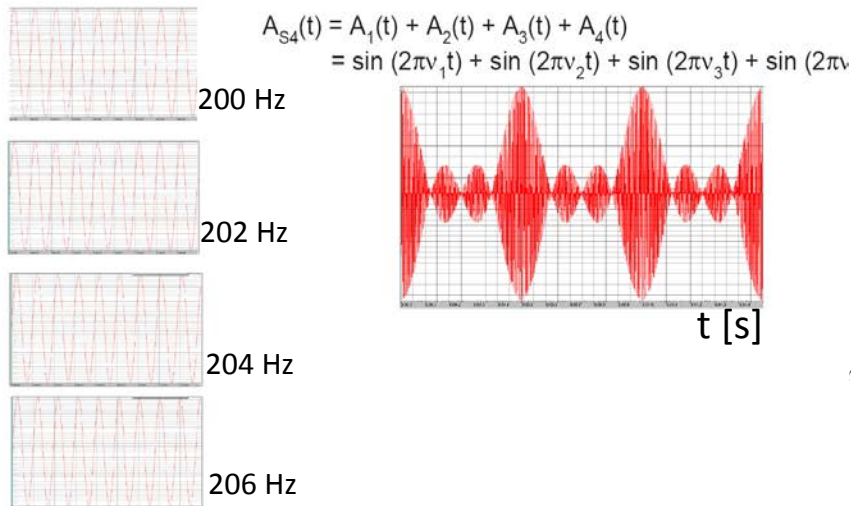
200 Hz

202 Hz

t [s]

Mode-locking regime

interference of waves
with four equidistant frequencies

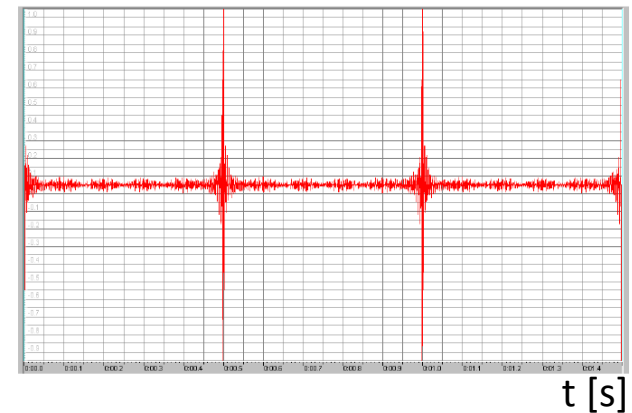


interference of waves
with 120 equidistant frequencies

$$A_{S120}(t) = \sum_{n=0}^{120} \sin[2\pi(\nu_1 + n\Delta\nu)t]$$

$$\nu_1 = 200 \text{ Hz}$$

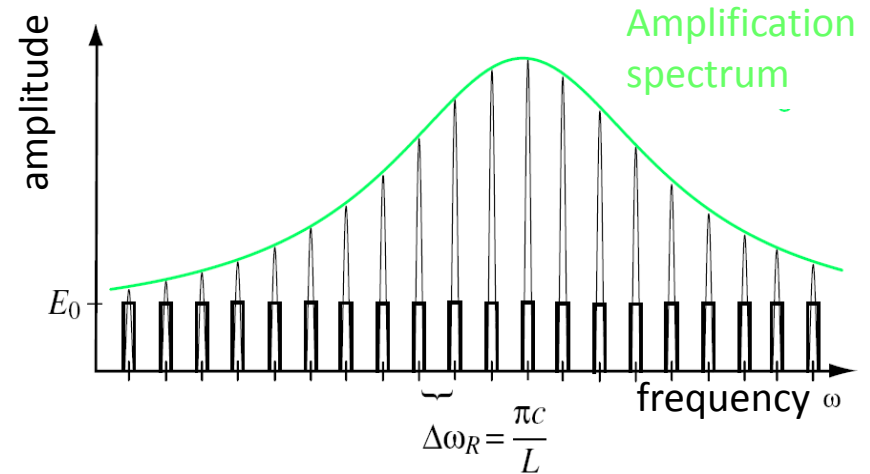
$$\Delta\nu = 2 \text{ Hz}$$



Mode-Locking

- Different interfering light waves are **longitudinal modes** of the resonator
- more modes \rightarrow shorter the pulse

- Typical mode-locked lasers have:
ultra short pulses $\sim 50 \text{ fs} - 1 \text{ ps}$
very high peak power $\sim 1 \text{ MW} - 10 \text{ GW}$



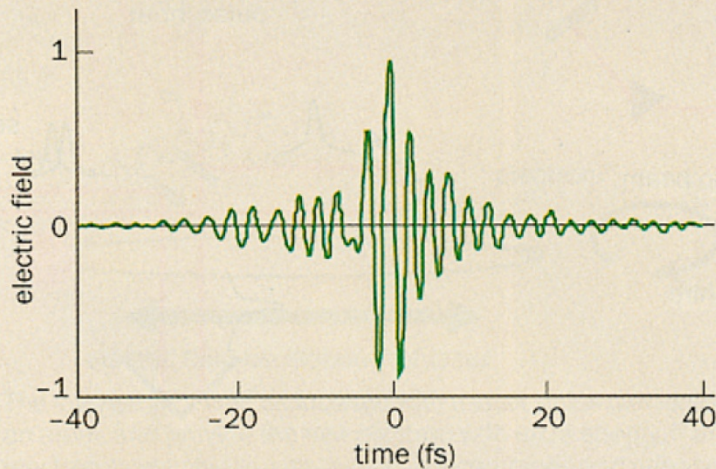
Heisenberg uncertainty principle: $\Delta\nu \cdot \Delta\tau \geq 1$

\Rightarrow very short light pulses cannot be very monochromatic \Rightarrow special active media with **broad emission spectrum** needed for very short (femtosecond) pulses

Ti:Sapphire is typical active medium for fs-lasers

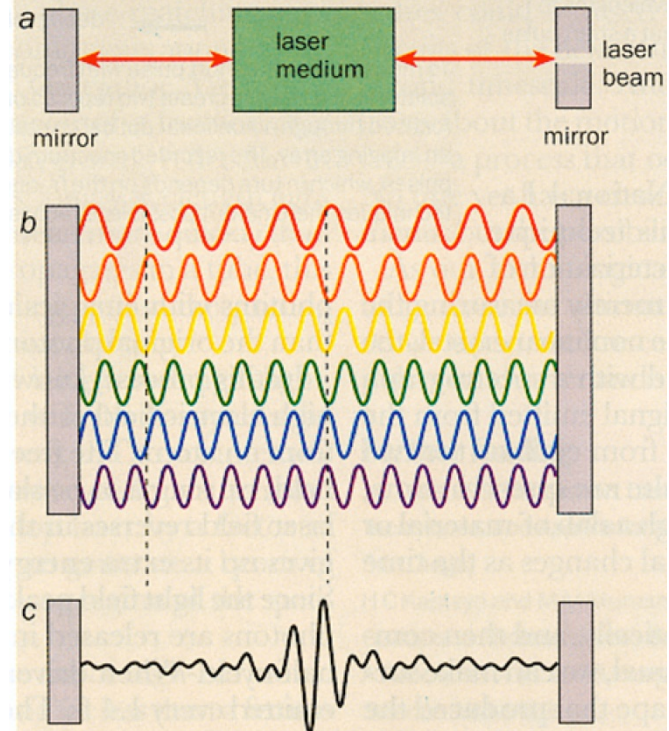
Examples of Ultra-short pulses

2 Short light pulses



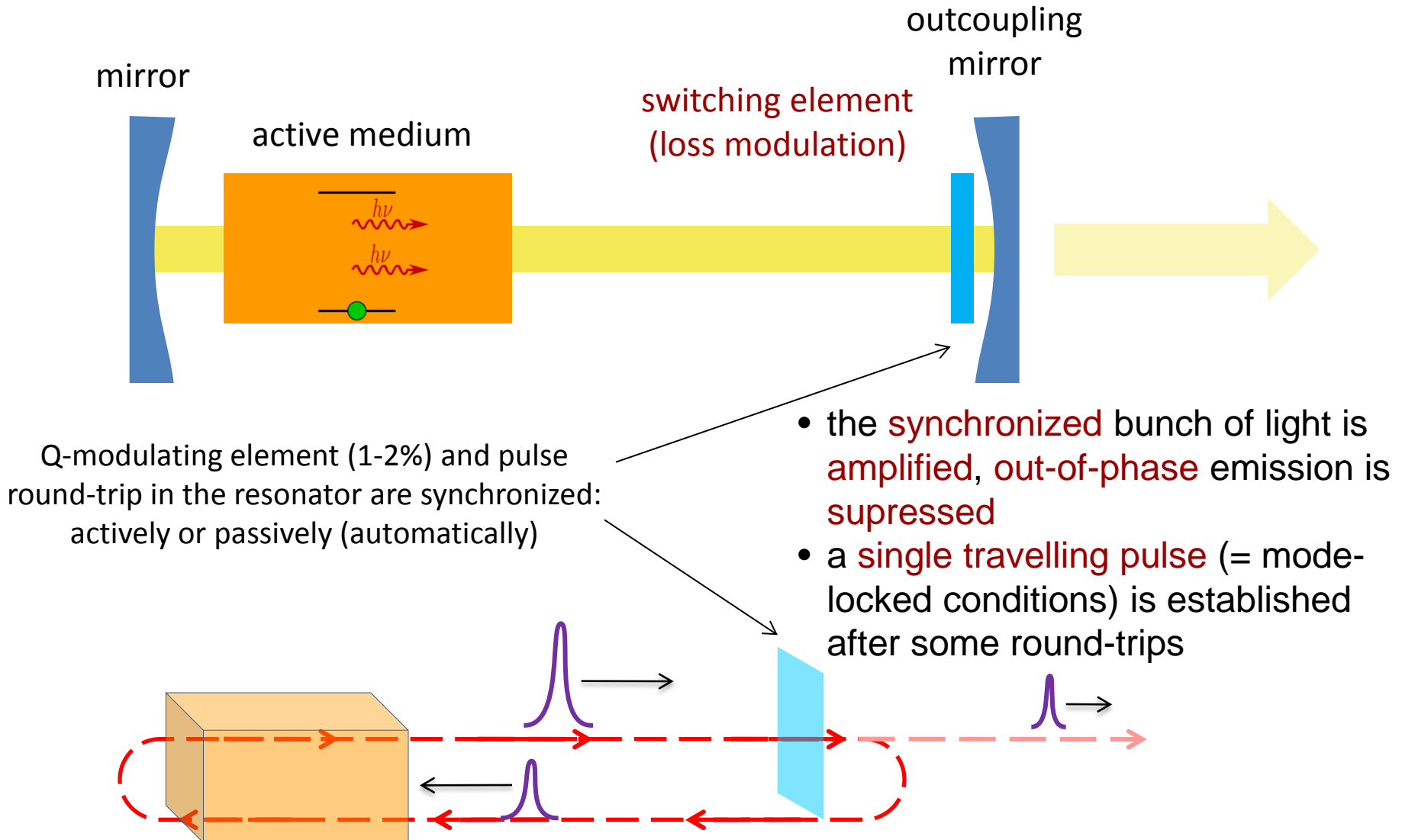
Maxim Pshenichnikov of the University of Groningen in the Netherlands has measured the electric field of a 5 fs light pulse, the shortest complete pulse measurement made to date. The output pulse consists of the two complete cycles centred around 0 fs.

3 Laser modes

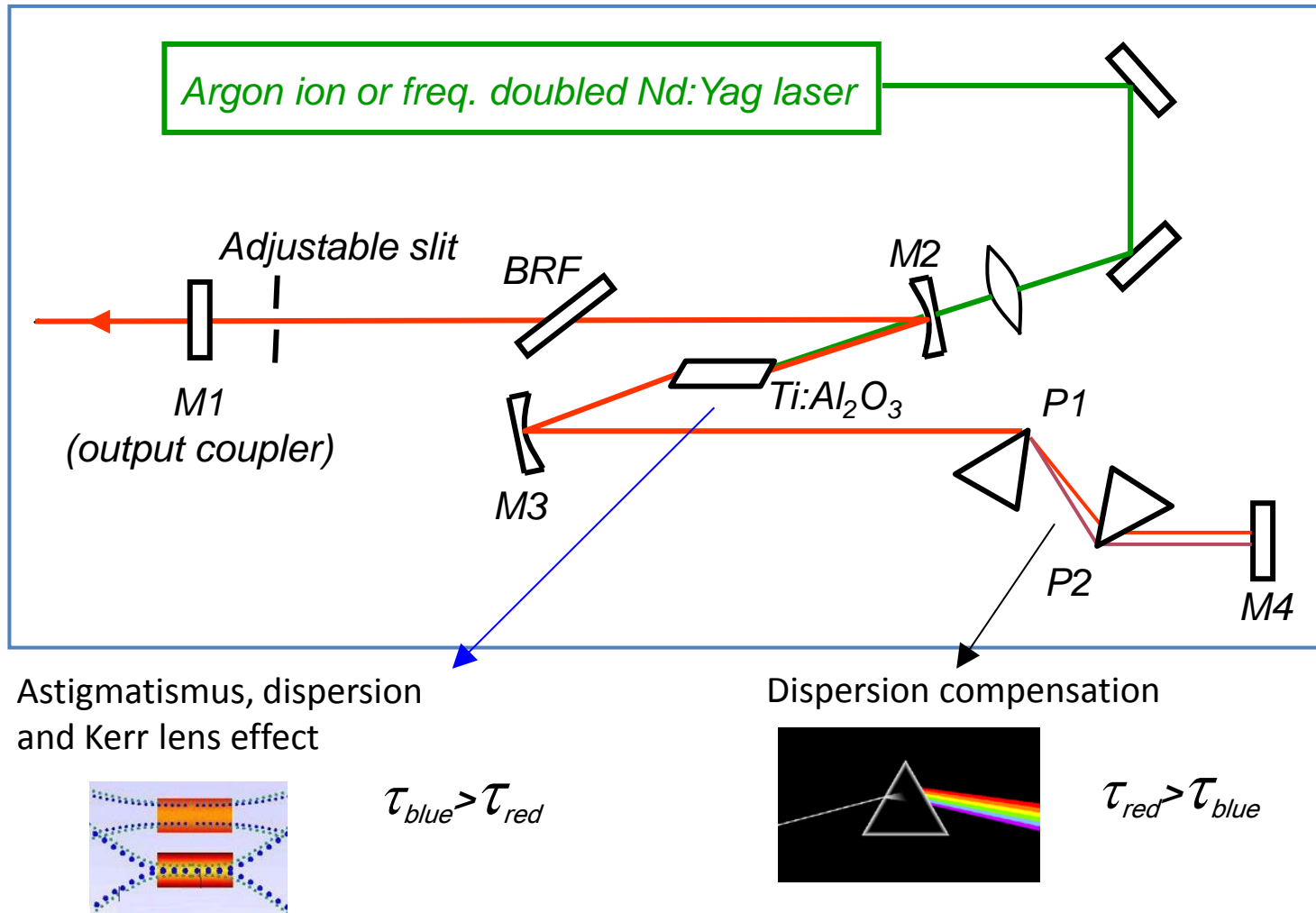


(a) A laser essentially consists of a laser medium sandwiched between two mirrors, one of which is partly transmissive. If the amplification of light by the laser medium is greater than the energy loss, light is emitted through the end mirror. (b) Many different modes can exist within the laser cavity, under the condition that the cavity length must equal an integer number of wavelengths. Each mode has a different frequency and wavelength. (c) In a mode-locked laser the electric field associated with the different modes must add constructively at one point and destructively elsewhere to create a high-intensity spike.

Modes couplés dans la pratique



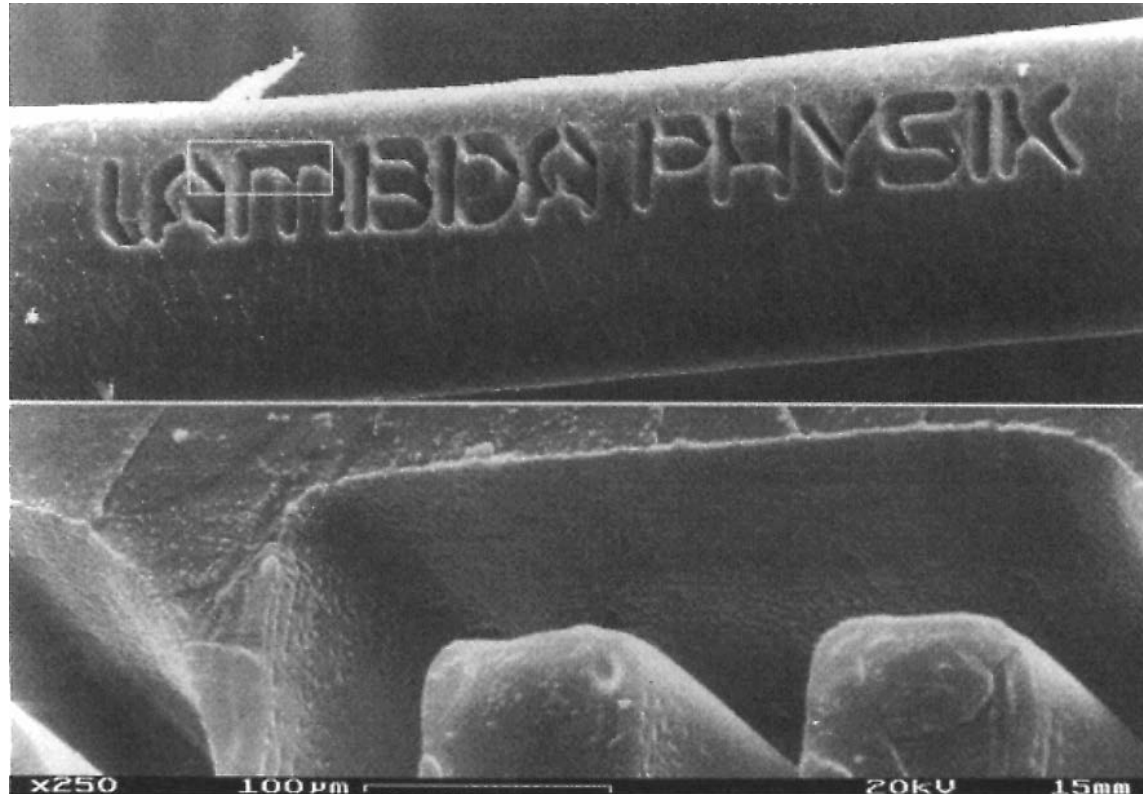
Schematics of a Femtosecond Laser



→ minimum pulse width: ~30 fs, special thin crystal and chirped mirrors: 4-5 fs

Example: Human Hair Marking

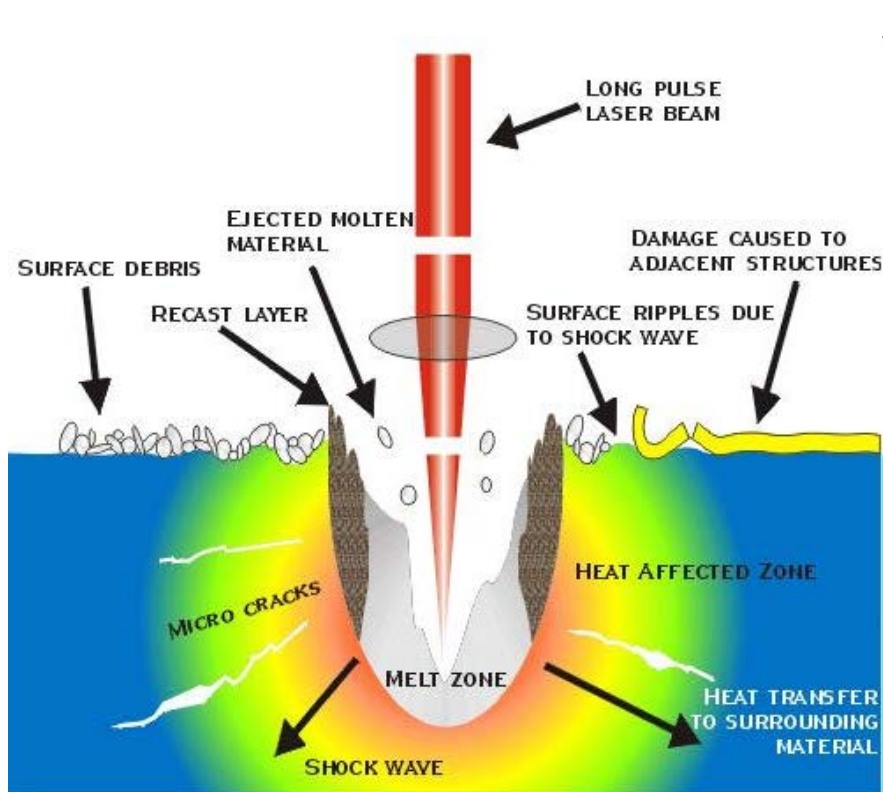
„Cold“
ablation?



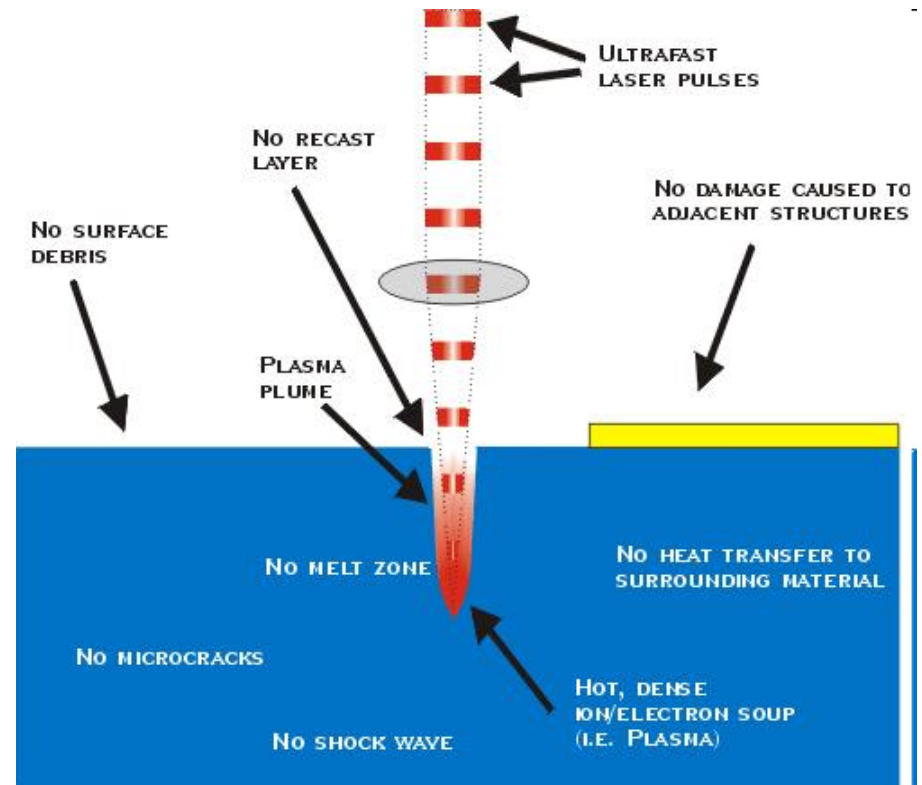
Scanning electron micrograph showing writing by excimer laser induced ablation on a human hair

Srinivasan, 1982, IBM Yorktown Heights;
Cold ablation by UV photon bond scission

ns-Machining vs. fs-Machining



©1999 Clark-MXR, Inc.



©1999 Clark-MXR, Inc.

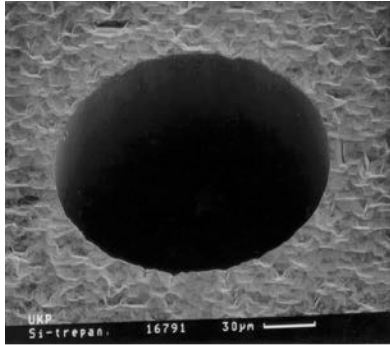


ns

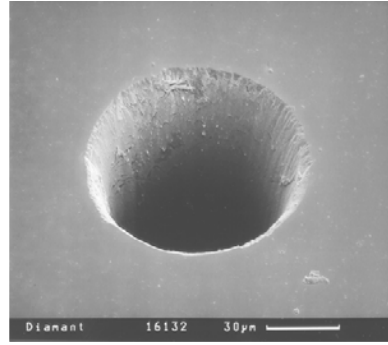


fs

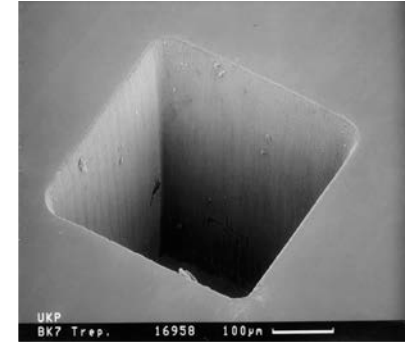
fs-Laser Machining



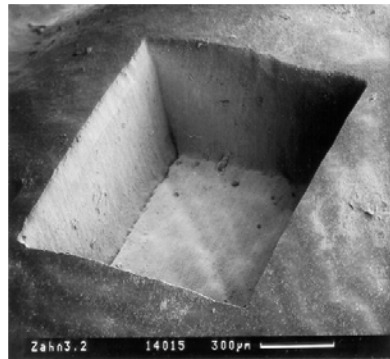
Silicon



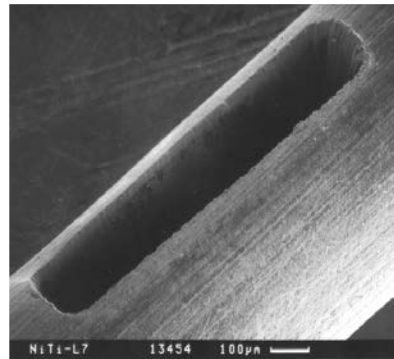
Diamond



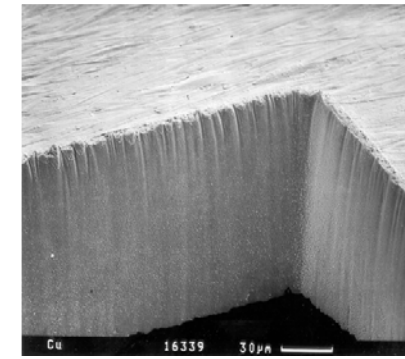
Glass



Tooth Enamel



Special Alloy

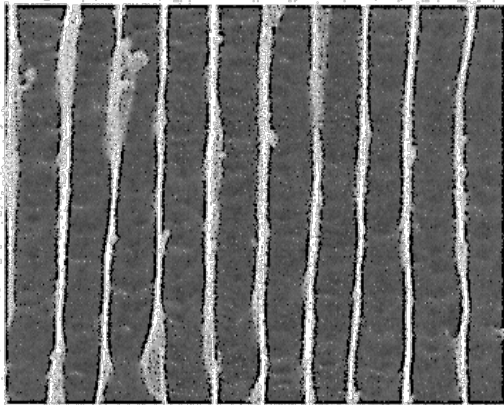


Copper

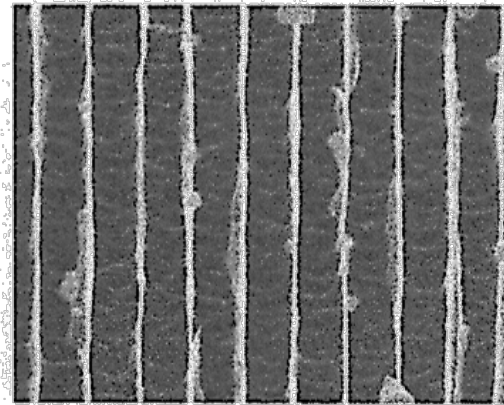
Ablation quality pulse duration

Material: Copper

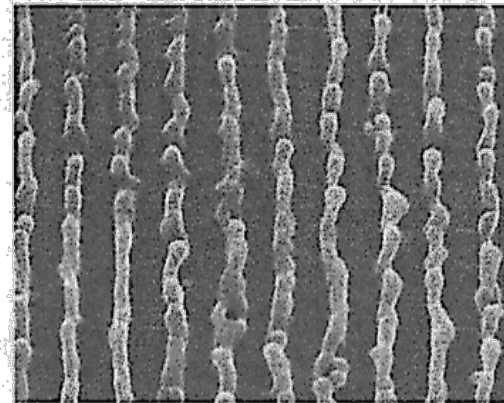
Laser: 248 nm, 600 mJ/cm², 1 pulse



0.5 ps



5 ps

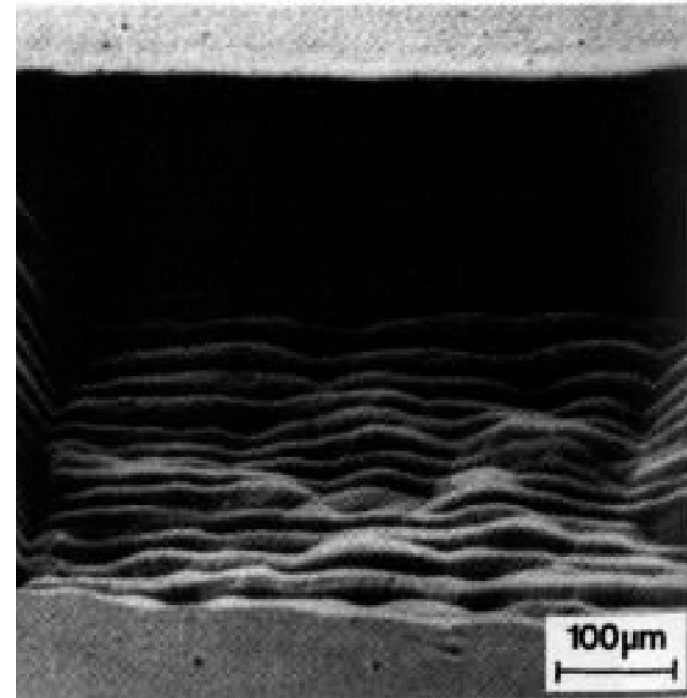
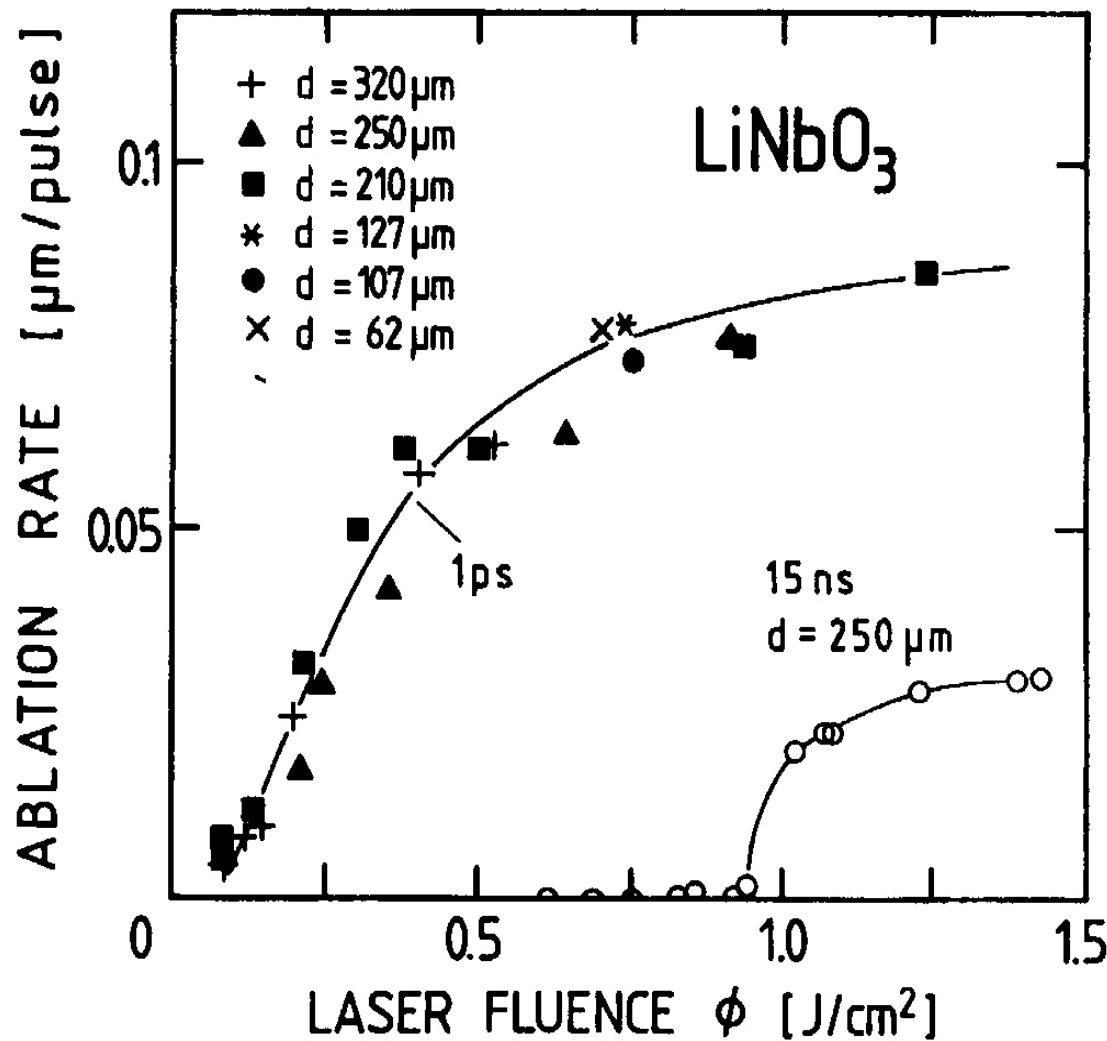


50 ps

1 μm

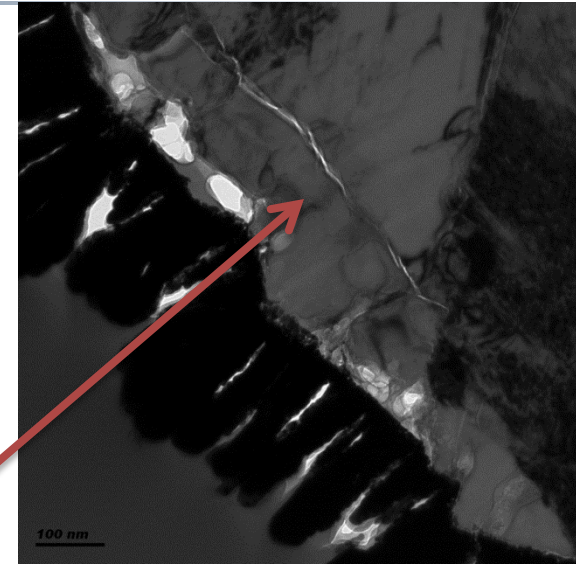
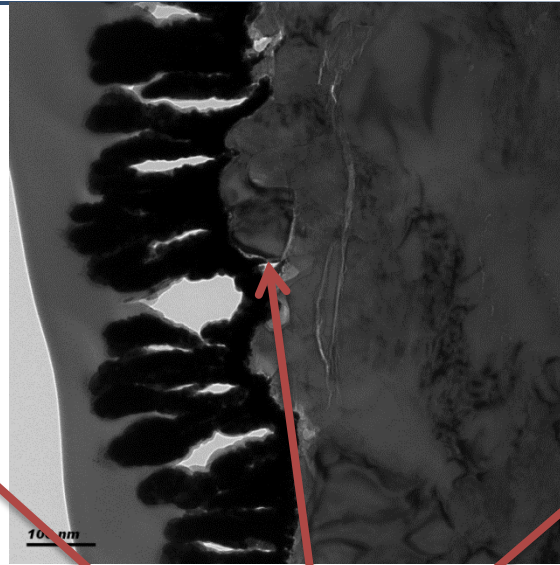
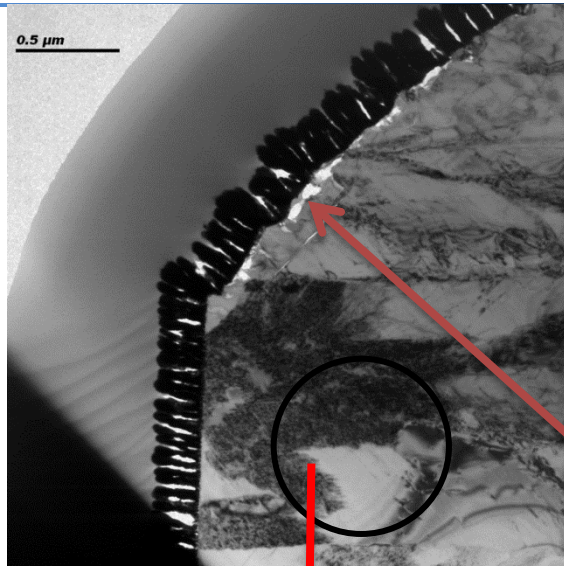
Laser-
Laboratorium
Göttingen e.V.

Ablation Influences



48 nm KrF-laser radiation. (a) Irradiation with $\phi = 4.2 \text{ J}/\text{cm}^2$. An undefined crater is visible in the center of the material. (b) Irradiation with fs pulses results in a relatively smooth surface and no cracks are observed.

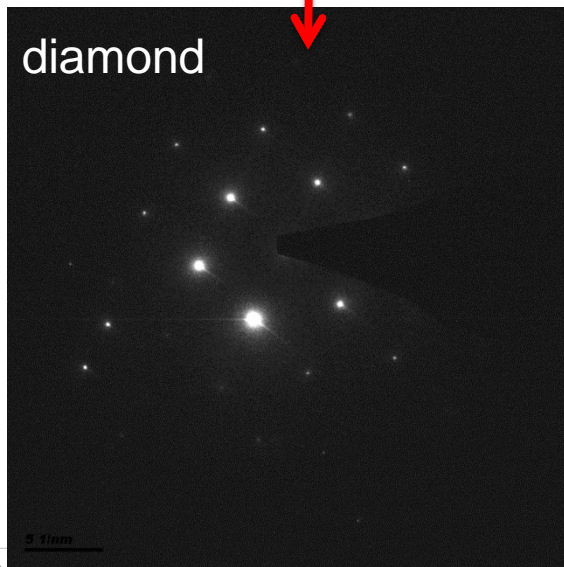
Diamond Ablation (ps)



**TEM
Images**

cracks

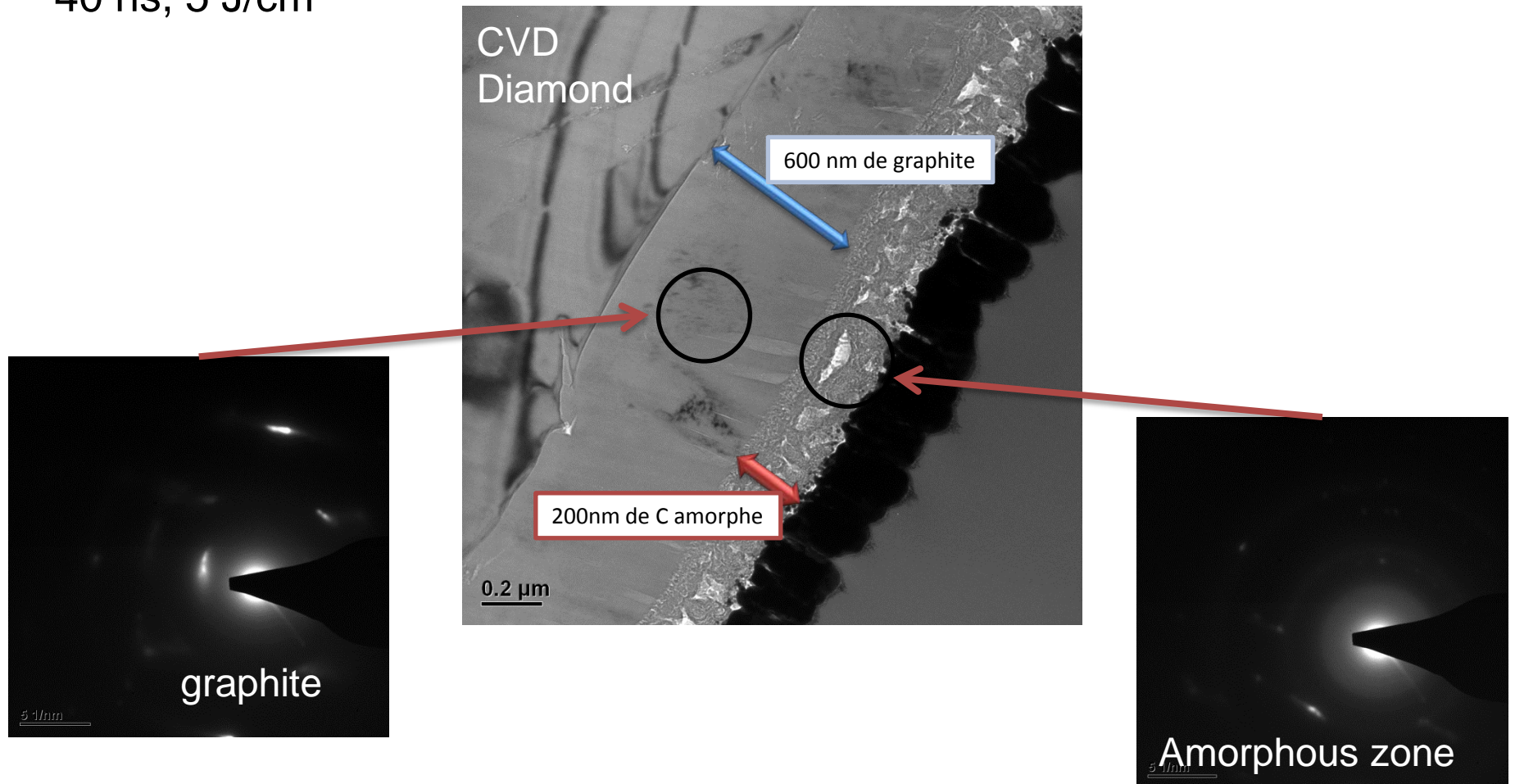
no graphite, no amorphous carbon



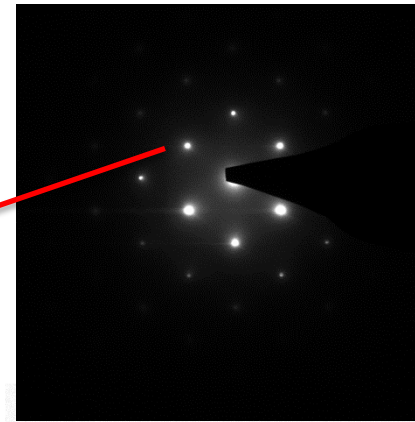
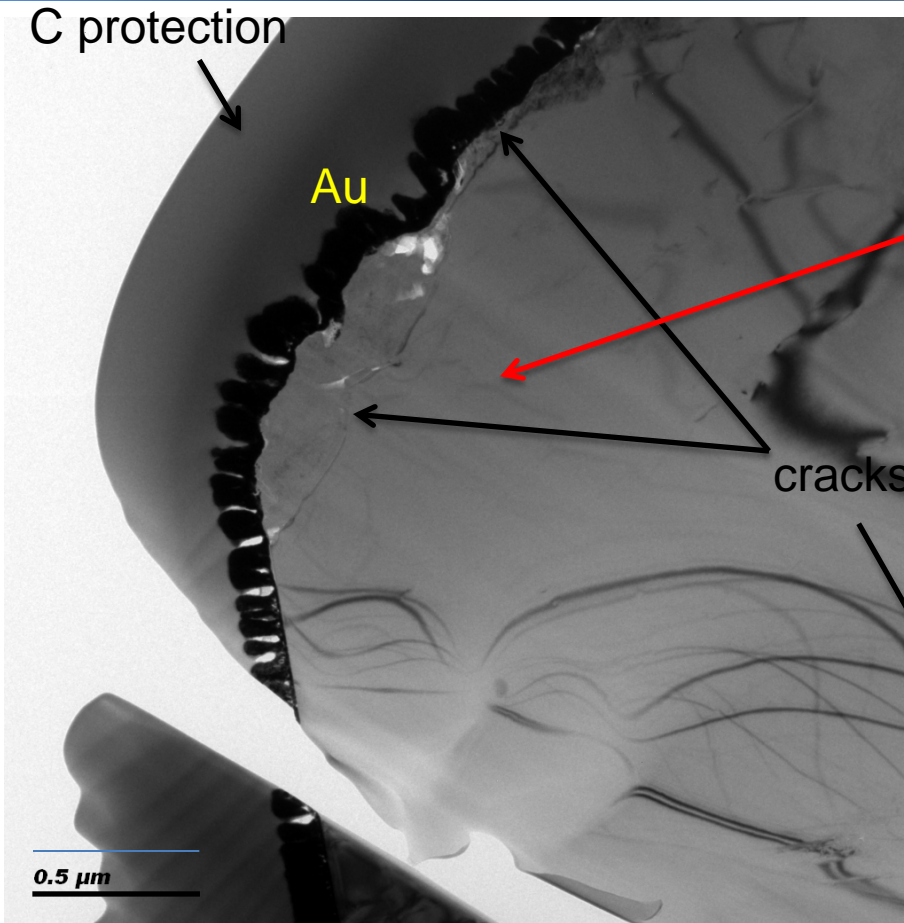
SHG Nd:YAG, 532 nm,
ps-pulses, 5.25 J/cm²

Diamond Ablation (ns) - Graphitization

SHG Nd:YAG, 532 nm,
40 ns, 5 J/cm²

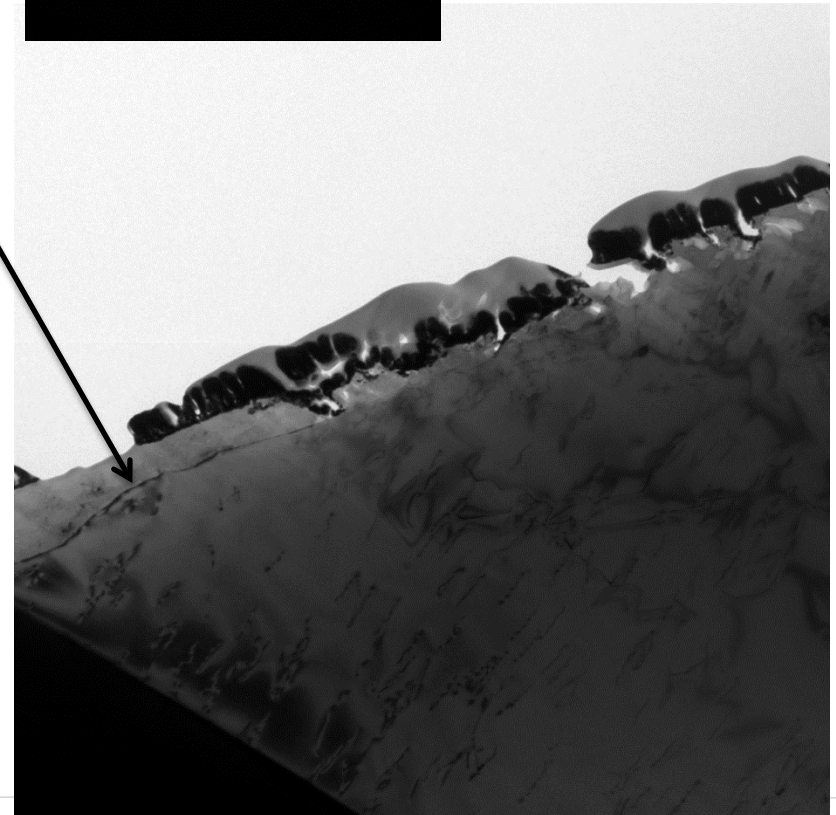


Diamond Ablation (ns) - Graphitization



TEM Images

no graphite –
only diamond



SHG Nd:YAG, 532 nm,
40 ns, 35.8 J/cm²